

VALUE PROPOSITION

- Among the highest **Thermal Conductivity** gap pads in industry
 - TGP 40000SF: **40 W/m.K**, not electrically insulating
 - TGP 18000SF: **18 W/m.K**, electrically insulating
 - TGP 12000SF: **12 W/m.K**, electrically insulating (in development)
- High z-axis thermal conductivity at lower-filler/higher-polymer loading than typical TIMs – enabled by novel **oriented filler technology**
 - Allows easier **handling** and retains elastomeric behavior in application
 - **Lightweight** – lower density, 1.7 gm/cc
- **Non-silicone**, non-reactive, no-cure chemistry
 - Low liquid migration – **low bleed** and **low out-gassing** – passed NASA test
- High **temperature reliability** for non-silicone – long-term 125–150°C
- **Sustainability** – no post-process, allows disassembly: repair, end-of-life
- **Usability** – broad **range of thickness**, 0.5–3.2mm (20–125mils)
 - Readily cut to **custom sizes and shapes**
 - Optional one-sided tackiness to facilitate **pick-and-place assembly process**
 - **Reworkable**, no messy clean-up



Product Format

- 2" (5cm) size – current pilot line
- 6" (15cm) size – Q2 2024 limited prod
- 10" (25cm) size – Q4 2024 full prod
- Thickness: 20, 40, 60, 80, 100, 125 mils
(0.5, 1.0, 1.5, 2.0, 2.5, 3.2 mm)

Development: 12mils (0.3mm)